L Number	Hits	Search Text	DB	Time stamp
16	732590	(liquid or fluid) and (flux or adhesive or	USPAT;	2004/05/11 15:12
		epoxy or resin or paste or cream)	US-PGPUB;	
		<u>-</u>	EPO; JPO;	
			DERWENT;	
19	55089	((liquid or fluid) and (flux or adhesive	IBM_TDB USPAT;	2004/05/11 15:14
17	33089	or epoxy or resin or paste or cream)) and	US-PGPUB;	2004/05/11 15:14
		(move or mov\$4 or plac\$6 or position\$4 or	EPO; JPO;	
		mount\$4) near (component or device or chip	DERWENT;	
		or die or wafer)	IBM_TDB	0004465455
20	30793	(((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and	USPAT;	2004/05/11 15:14
		(move or mov\$4 or plac\$6 or position\$4 or	US-PGPUB; EPO; JPO;	
		mount\$4) near (component or device or chip	DERWENT;	
		or die or wafer)) and adhesive	IBM_TDB	
21	1898	((((liquid or fluid) and (flux or adhesive	USPAT;	2004/05/11 15:15
		or epoxy or resin or paste or cream)) and	US-PGPUB;	
		(move or mov\$4 or plac\$6 or position\$4 or mount\$4) near (component or device or chip	EPO; JPO; DERWENT;	
	-	or die or wafer)) and adhesive) and (cure	IBM TDB	
		or curing or cured) near adhesive		
22	98	(((((liquid or fluid) and (flux or	USPAT;	2004/05/11 15:16
		adhesive or epoxy or resin or paste or	US-PGPUB;	
		cream)) and (move or mov\$4 or plac\$6 or position\$4 or mount\$4) near (component or	EPO; JPO; DERWENT;	
		device or chip or die or wafer)) and	IBM TDB	
		adhesive) and (cure or curing or cured)		
		near adhesive) and (chang\$4 or shift\$4)		
23	69	near (phase or state)	HODAM	2004/05/22 25 25
23	69	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or	USPAT; US-PGPUB;	2004/05/11 15:16
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
		device or chip or die or wafer)) and	IBM_TDB	
		adhesive) and (cure or curing or cured)		
		near adhesive) and (chang\$4 or shift\$4) near (phase or state)) and epoxy		
24	46	((((((liquid or fluid) and (flux or	USPAT;	2004/05/11 15:16
		adhesive or epoxy or resin or paste or	US-PGPUB;	, ,
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
		device or chip or die or wafer)) and adhesive) and (cure or curing or cured)	IBM_TDB	
		near adhesive) and (chang\$4 or shift\$4)		
	,	near (phase or state)) and (solder or		
26	120	paste or cream)	HODAE	2004/05/22 25 25
26	132	(((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or	USPAT; US-PGPUB;	2004/05/11 15:17
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
		device or chip or die or wafer)) and	IBM_TDB	
		adhesive) and (cure or curing or cured)		
		near adhesive) and (chang\$4 or shift\$4 or increas\$6 or decreas\$4) near (pressure)		
27	110	(((((liquid or fluid) and (flux or	USPAT;	2004/05/11 15:20
	*	adhesive or epoxy or resin or paste or	US-PGPUB;	
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
!		device or chip or die or wafer)) and adhesive) and (cure or curing or cured)	IBM_TDB	
	İ	near adhesive) and (chang\$4 or shift\$4 or		'
		increas\$6 or decreas\$4) near (vol or		
	. =	volume or expan\$7 or contract\$7)		
28	43	(((((liquid or fluid) and (flux or	USPAT;	2004/05/11 15:18
		adhesive or epoxy or resin or paste or cream)) and (move or mov\$4 or plac\$6 or	US-PGPUB; EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
		device or chip or die or wafer)) and	IBM_TDB	
		adhesive) and (cure or curing or cured)	-	
		near adhesive) and (chang\$4 or shift\$4 or		
		increas\$6 or decreas\$4) near (potential)		

		1////3: '3 - 57 :3\ 3 /63	Lizanam	T 0 0 0 1 / 0 = 3
29	1031	(((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or	USPAT; US-PGPUB;	2004/05/11 15:19
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
	1.	device or chip or die or wafer)) and	IBM_TDB	
		adhesive) and (cure or curing or cured)		
		near adhesive) and (chang\$4 or shift\$4 or		
	1	increas\$6 or decreas\$4 or high\$4 or low\$4)		
30	548	near (temperature) ((((((liquid or fluid) and (flux or	USPAT;	2004/05/11 15:19
30	. 540	adhesive or epoxy or resin or paste or	US-PGPUB;	2004/05/11 15:19
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	}
		device or chip or die or wafer)) and	IBM_TDB	
		adhesive) and (cure or curing or cured)		
		near adhesive) and (chang\$4 or shift\$4 or		
		increas\$6 or decreas\$4 or high\$4 or low\$4) near (temperature)) and dimension		
31	72		USPAT;	2004/05/11 15:23
		adhesive or epoxy or resin or paste or	US-PGPUB;	1 2001, 00, 11 13.23
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
		device or chip or die or wafer)) and	IBM_TDB	
		adhesive) and (cure or curing or cured) near adhesive) and (chang\$4 or shift\$4)		
		near (phase or state)) and (optic\$4 adj		
	1.	(fiber or fibre) or (fiber or fibre) adj		
		optic\$4 or laser or lens or led or diode)		
32	68	((((((liquid or fluid) and (flux or	USPAT;	2004/05/11 15:21
		adhesive or epoxy or resin or paste or	US-PGPUB;	
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or device or chip or die or wafer)) and	DERWENT; IBM TDB	
		adhesive) and (cure or curing or cured)	151-1-155	
		near adhesive) and (chang\$4 or shift\$4 or		
		increas\$6 or decreas\$4) near (vol or		
		volume or expan\$7 or contract\$7)) and		
22		(cool\$6 or quench\$6)		000.405/44 45 04
33	89	<pre>(((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or</pre>	USPAT;	2004/05/11 15:21
		cream)) and (move or mov\$4 or plac\$6 or	US-PGPUB; EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
		device or chip or die or wafer)) and	IBM TDB	
		adhesive) and (cure or curing or cured)		
		near adhesive) and (chang\$4 or shift\$4 or		
		increas\$6 or decreas\$4) near (vol or		
		volume or expan\$7 or contract\$7)) and (expand\$4 or expans\$4)		
34	0	((((((liquid or fluid) and (flux or	USPAT;	2004/05/11 15:22
		adhesive or epoxy or resin or paste or	US-PGPUB;	
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
		device or chip or die or wafer)) and	IBM_TDB	
		adhesive) and (cure or curing or cured) near adhesive) and (chang\$4 or shift\$4 or		
		increas\$6 or decreas\$4) near (vol or		
		volume or expan\$7 or contract\$7)) and sump		:
35	11	((((((liquid or fluid) and (flux or	USPAT;	2004/05/11 15:23
		adhesive or epoxy or resin or paste or	US-PGPUB;	, .
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or device or chip or die or wafer)) and	DERWENT; IBM_TDB	
		adhesive) and (cure or curing or cured)	10.1_108	
		near adhesive) and (chang\$4 or shift\$4 or		
		increas\$6 or decreas\$4) near (vol or		
		volume or expan\$7 or contract\$7)) and		
		(tank or container or vat or bath or		
		reservoir or pot or supply) near (liquid		
	1.	or fluid or adhesive or epoxy or rosin or resin or cream or paste or solder)		
	J		L	<u> </u>

36	71	((((((liquid or fluid) and (flux or	USPAT;	2004/05/11 15:24
"	'-	adhesive or epoxy or resin or paste or	US-PGPUB;	2004/03/11 13.24
Ì		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
		device or chip or die or wafer)) and	IBM TDB	
		adhesive) and (cure or curing or cured)	_	
	•	near adhesive) and (chang\$4 or shift\$4 or		!
		increas\$6 or decreas\$4) near (vol or		
	ŀ	volume or expan\$7 or contract\$7)) and		
		(optic\$4 adj (fiber or fibre) or (fiber or		
		fibre) adj optic\$4 or laser or lens or led		
İ		or diode)		
37	91	(((((= 4 = 2 = 2 = 2 = 2 = 2 = 2 = 2 = 2 = 2	USPAT;	2004/05/11 15:23
		adhesive or epoxy or resin or paste or	US-PGPUB;	,
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
Ī	Ì	device or chip or die or wafer)) and	IBM_TDB	·
		adhesive) and (cure or curing or cured) near adhesive) and (chang\$4 or shift\$4)		
		near (phase or state)) and heat\$4		
39	65	1	USPAT;	2004/05/11 15:24
37	"	adhesive or epoxy or resin or paste or	US-PGPUB;	2004/05/11 15:24
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
		device or chip or die or wafer)) and	IBM TDB	
		adhesive) and (cure or curing or cured)		
		near adhesive) and (chang\$4 or shift\$4)		
		near (phase or state)) and heat\$4) and		
		(optic\$4 adj (fiber or fibre) or (fiber or		
ĺ		fibre) adj optic\$4 or laser or lens or led		
		or diode)		
25	13	· · · · · · · · · · · · · · · · ·	USPAT;	2004/05/11 15:26
		adhesive or epoxy or resin or paste or	US-PGPUB;	
		cream)) and (move or mov\$4 or plac\$6 or	EPO; JPO;	
		position\$4 or mount\$4) near (component or	DERWENT;	
		device or chip or die or wafer)) and	IBM_TDB	
		adhesive) and (cure or curing or cured)		
		near adhesive) and (chang\$4 or shift\$4 or	٠.٠	
		increas\$6 or decreas\$4) near (surface adj		
		tension)		